MINEWSEMI

Small Wi-Fi 6 + BLE 5.3 Combo Module

ME16WS03

Datasheet

V 1.0.0

Version Note

Version	Details	Contributor(s)	Date	Notes
1.0.0	First edit	Vincle, Leo	2024.10.12	

Part Number

Model	Hardware Code
ME16WS03	3Y40TI

Click the icon to view and download the latest product documents electronically.
https://en.minewsemi.com/file/ME16WS03-nRF7002+nRF5340_Datasheet_K_EN.pdf

ME16WS03-nRF7002+nRF5340

Dual-Core, High-performance, Ultra-low-power, Support AP/STA Mode, Support Wi-Fi 6 Dual-band 2.4G & 5G, Small dimensions

ME16WS03 Wi-Fi 6+BLE Combo Module adopts integrated WLCSP nRF7002 and WLCSP nRF5340 chip, supports BLE mode, at the same time supports Wi-Fi 6 dual-band connection, 2.4G and 5G function, 1T1R. WiFi maximum rate is 86mbps, output power can reach up to 21dBm, receiving current is 56mA in 2.4G band, and 58mA in 5G band. It supports BLE master-slave mode and transparent transmission mode. It adopts independent antenna design for WiFi and BLE, which does not interfere with each other, and the antenna interface is IPEX. One device can support two wireless connection modes, WiFi and BLE.

FEATURES

- Bluetooth 5.3
- Dual-core
- Ultra-low-power
- Small dimensions
- Support Wi-Fi 6 dual-band 2.4G and 5G, 1T1R
- High-performance

KEY PARAMETER

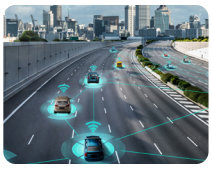
ME16WS03			
Chip Model	nRF7002+nRF5340	**Antenna**	IPEX
Module Size	23.2×16×3.6mm	**GPIO**	23
Flash	1MB+256KB	**RAM**	512KB+64KB
Receiving Sensitivity	-98dBm	**Transmission Power**	BLE:-40 ~ +3dBm WiFi:+21dBm
Current(TX)	2.4G-191mA 5G-260mA	**Current(RX)**	2.4G-56mA 5G-58mA
Firmware	/		

APPLICATION

Smart Buildings

Consumer Electronics

Smart Healthcare



Automotive Devices

Intelligent Wearable Device

Smart Agriculture

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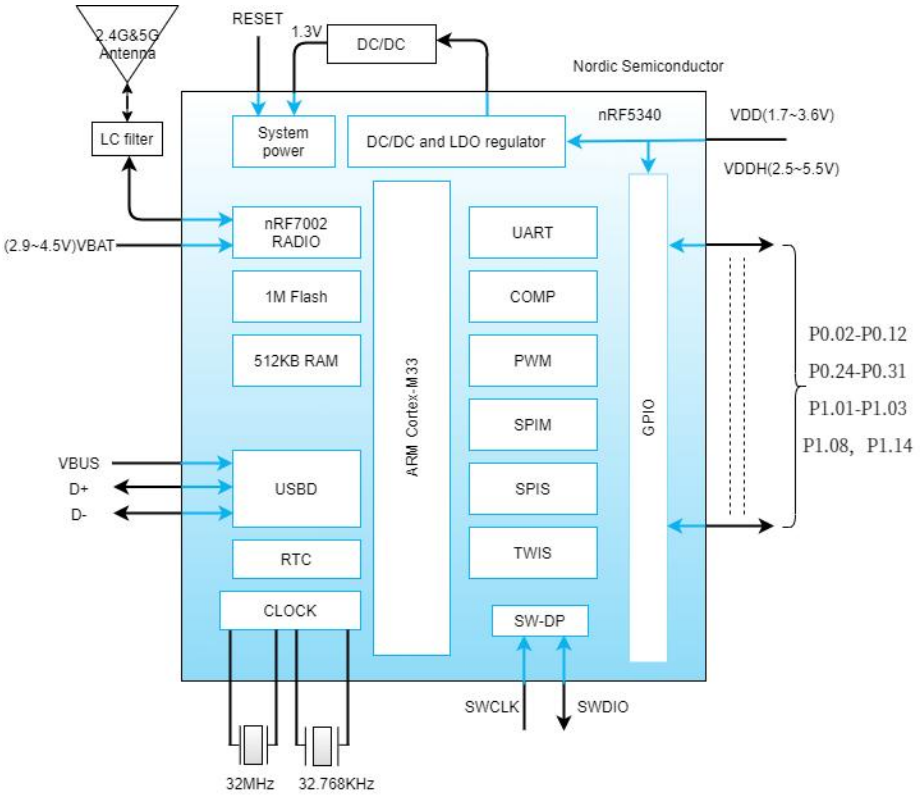
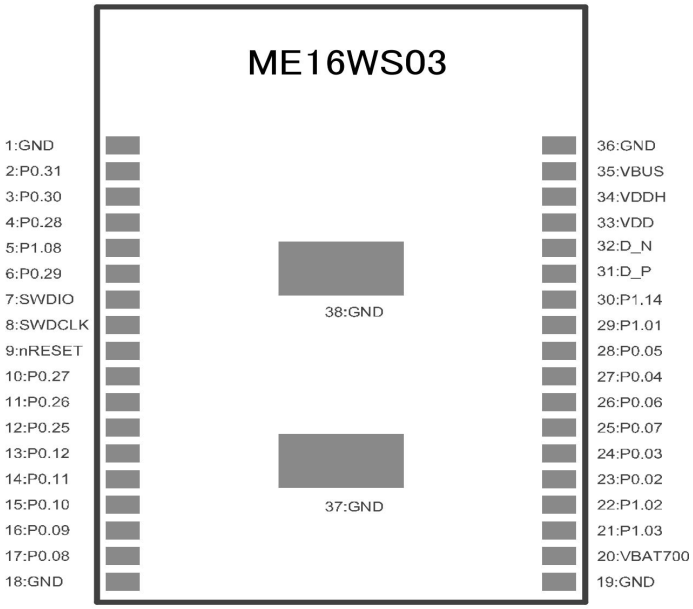
1 BLOCK DIAGRAM



2 ELECTRICAL SPECIFICATION

Parameter	Values	Notes
Operation Voltage	1.7V-5.5V	To ensure RF operation, the BLE power supply voltage is recommended to be no less than 3.3V WiFi supply voltage is recommended to be no less than 3.6V
Working Temperature	-40℃~+85℃	
Transmission Power	BLE:-40 ~ +3dBm WiFi: +5 ~+21dBm	Configurable
Current (RX)	2.4G-56mA/5G-58mA	
Current (TX)	2.4G-191mA/5G-260mA	BLE 2Mbps transmission
Module Dimension	23.2x16x3.6mm	
Quantity of IO Port	23	USB/UART/ADC

3 PIN DESCRIPTION

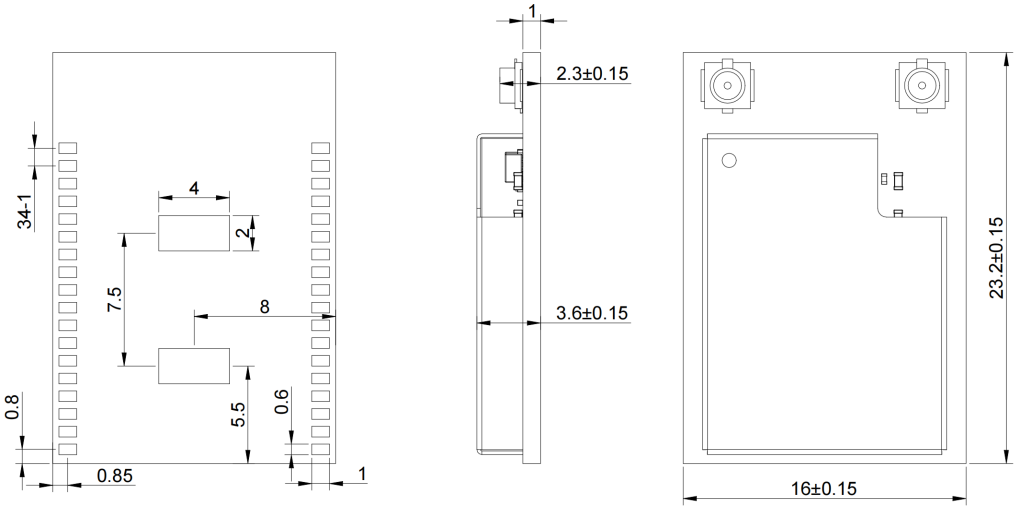


(Top View)

4 PIN DEFINITION

Symbol	Type	Definition
VDD	Power positive pole	Supply electricity: 1.7V~3.6V
VDDH	GPIO	Supply electricity: 2.5V~5.5V
VBUS	Power source	USB interface acquired power input after conversion
VBAT70	Power source	WiFi power supply, 2.9V~4.5V, 3.6V standard
GND	Negative power supply	Grounded
SWDCLK/SWDIO	I/O, SWCLK/SWDIO	For burning firmware
P0.02-P0.12	GPIOs	General purpose IO interface
P0.24-P0.31	GPIOs	General purpose IO interface
P1.01-P1.03	GPIOs	General purpose IO interface
P1.08，P1.14	GPIOs	General purpose IO interface
D_P	USB port	USB D+
D_N	USB port	USB D-
RESET	Reset	Pull up the resistor internally to reset

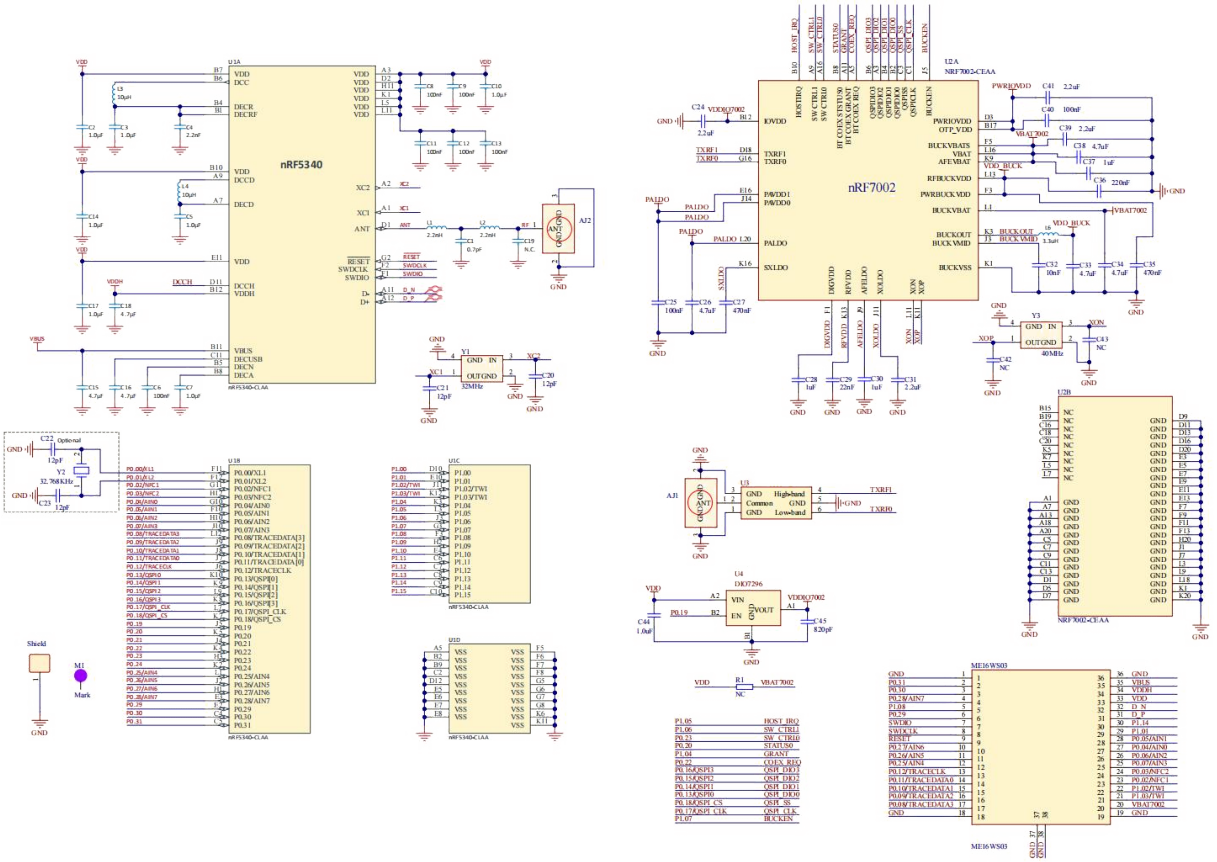
5 MECHANICAL DRAWING



Default unit: mm Default tolerance: ±0.15

Notice: The recommended pad size suggest 1.0*0.6mm, Pad interval 1mm

6 ELECTRICAL SCHEMATIC



Before placing an order, please confirm the specific configuration required with the salesperson.

7 POWER SUPPLY USE

7.1 Power Supply

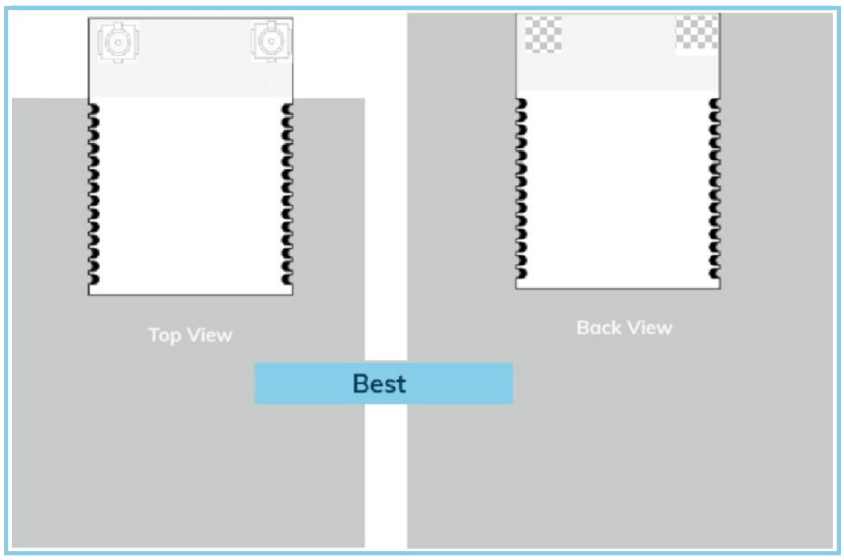
BLE Chip operation voltage range is 2.7V to 3.6V, to ensure normal use, supply voltage range should be 3.0V to 3.6V as far as possible.

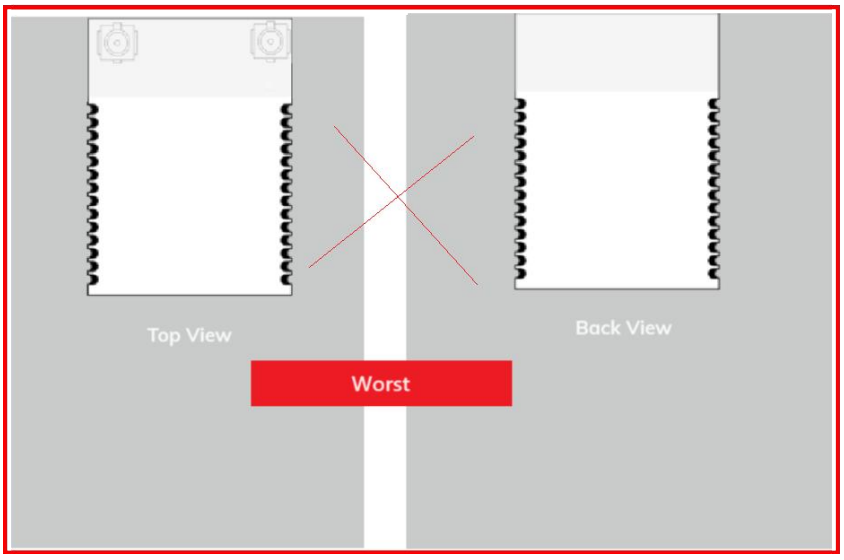
WiFi Chip operation voltage range is 2.9V to 4.5V, to ensure normal use, supply voltage range should be 3.3V to 4.5V as far as possible.

8 PCB LAYOUT

There should be no GND plane or metal cross wiring in the module antenna area, and no components should be placed nearby. It is best to make a hollow or clear area, or place it on the edge of the PCB board.

Notice: The reference example is as follows. It is strongly recommended to use the first design method. The module antenna design is debugged according to the first wiring.



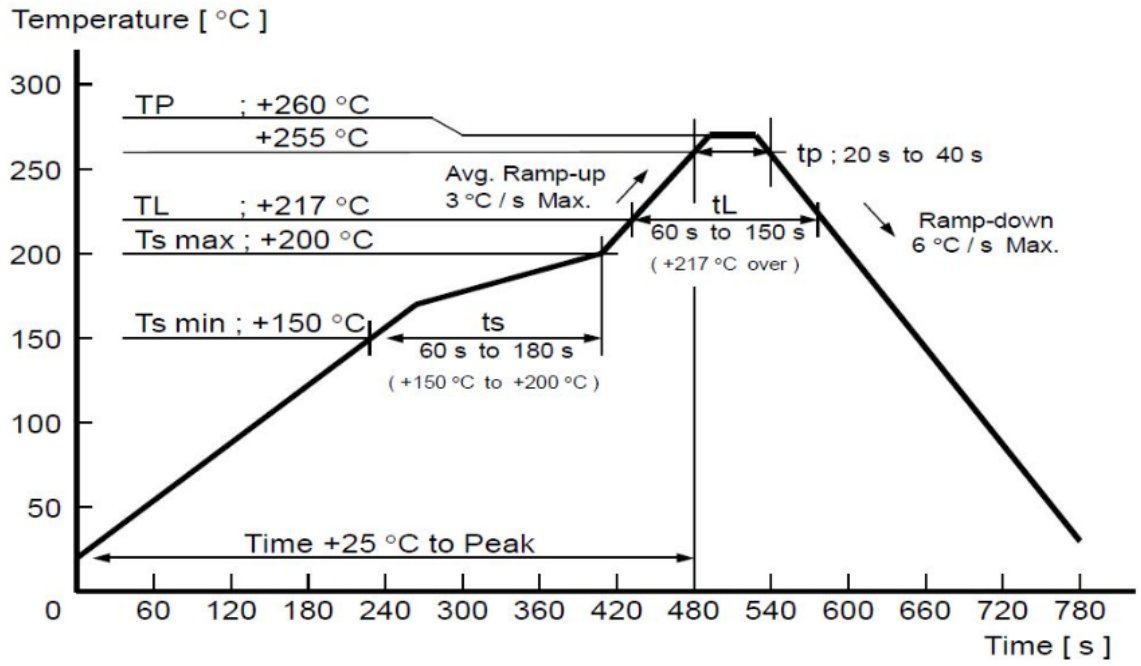


Layout Notes:

1) Preferred Module antenna area completely clearance and not be prevented by metals, otherwise it will influence antenna's effect (as above DWG. indication).
2) Cover the external part of module antenna area with copper as far as possible to reduce the main board's signal cable and other disturbing.
3) It is preferred to have a clearance area of 4 square meter or more area around the module antenna (including the shell) to reduce the influence to antenna.
4) Device should be grounded well to reduce the parasitic inductance.
5) Do not cover copper under module's antenna in order to avoid affect signal radiation or lead to transmission distance affected.
6) Antenna should keep far from other circuits to prevent radiation efficiency reduction or affects the normal operation of other lines.
7) Module should be placed on edge of circuit board and keep a distance away from other circuits.
8) Suggesting to use magnetic beads to insulate module's access power supply.

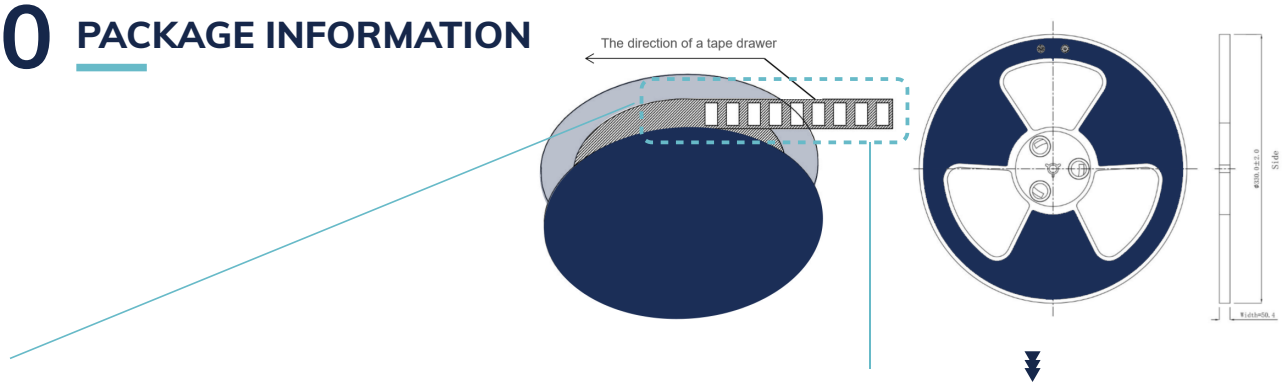
9 REFLOW AND SOLDERING

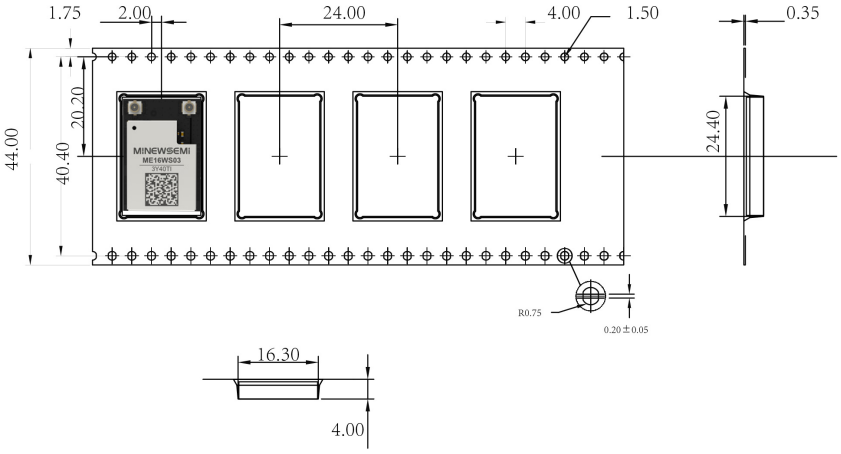
1) Do SMT according to above reflow oven temperature deal curve. Max. Temperature is 260℃;
Refer to IPC/JEDEC standard; Peak TEMP<260℃; Times: ≤2 times, suggest only do once reflow soldering on module surface in case of SMT double pad involved. Contact us if special crafts involved.



2) Suggesting to make 0.2mm thickness of module SMT for partial ladder steel mesh, then make the opening extend 0.8mm
3) After unsealing, it cannot be used up at one time, should be vacuumed for storage, couldn't be exposed in the air for long time. Please avoid getting damp and soldering-pan oxidizing. If there are 7 to 30 days interval before using online SMT, suggest to bake at 65-70 ℃ for 24 hours without disassembling the tape.
4) Before using SMT, please adopt ESD protection measure.

10 PACKAGE INFORMATION





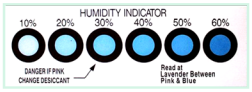
Inner carton(*5)
355*345*65mm，±5mm

Outer carton
370*358*350mm，±10mm

Remarks

General material list for FCL packaging:

Carrier tape packaging tray



Humidity Indicator
(1 pcs/bag)

Desiccant
(placed in a vacuum bag)

Vacuum bag

Inner carton(*5)
355*345*65mm，±5mm

Outer carton
370*358*350mm，±10mm

Other:

Moisture-proof label (attached to the vacuum bag)

Certification label (attached to the vacuum bag)

Outer box label

⚠ Default unit：mm Default tolerance：±0.1

Packing detail	Specification	Net weight	Gross weight	Dimension
ME16WS03	620PCS	-	-	W=44mm，T=0.35mm

⚠ Note: Default weight tolerance all are within 10g（except the special notes）

11 STORAGE CONDITIONS

- **Please use this product within 6 months after signing the receipt.**
  - This product should be stored without opening the package at an ambient temperature of 5~35°C and a humidity of 20~70%RH.
  - This product should be left for more than 6 months after receipt and should be confirmed before use.
  - The product must be stored in a non-corrosive gas (Cl2, NH3, SO2, NOx, etc.).
  - To avoid damaging the packaging material, do not apply any excessive mechanical shocks, including but not limited to sharp objects adhering to the packaging material and product dropping.

- **This product is suitable for MSL2 (based on JEDEC standard J-STD-020).**
  - After opening the package, the product must be stored at ≤30°C/<60%RH. It is recommended to use the product within 3-6 months after opening the package.
  - When the color of the indicator in the package changes, the product should be baked before welding.

- **Baking is not required for one year if exposure is limited to <30°C and 60%RH. Refer to MSL2 for exposure criteria for moisture sensitivity level. If exposed to (≥168h@85°C/60%RH) conditions or stored for more than one year, recommended baking conditions.**
  1. 120 +5/-5°C, 8 hours, 1 time
  Products must be baked individually on heat-resistant trays because the materials (base tape, reel tape, and cover tape) are not heat-resistant, and the packaging material may be deformed at temperatures of 120℃;
  2、90℃ +8/-0℃，24hours，1times
  The base tape can be baked together with the product at this temperature. Please pay attention to the uniformity of heat.

12 HANDLING CONDITIONS

• Be careful in handling or transporting products because excessive stress or mechanical shock may break products.

• Handle with care if products may have cracks or damages on their terminals. If there is any such damage, the characteristics of products may change. Do not touch products with bare hands that may result in poor solder ability and destroy by static electrical charge.

13 QUALITY

Cognizant of our commitment to quality, we operate our own factory equipped with state-of-the-art production facilities and a meticulous quality management system. We hold certifications for ISO9001, ISO14001, ISO27001, OHSA18001, BSCI.

Every product undergoes stringent testing, including transmit power, sensitivity, power consumption, stability, and aging tests. Our fully automated module production line is now in full operation, boasting a production capacity in the millions, capable of meeting high-volume production demands.

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15 RELATED DOCUMENTS

- MinewSemi_Product_Naming_Reference_Manual_V1.0
  https://en.minewsemi.com/file/MinewSemi_Product_Naming_Reference_Manual_EN.pdf
- MinewSemi_Connectivity_Module_Catalogue_V2.0
  https://en.minewsemi.com/file/MinewSemi_Connectivity_Module_Catalogue_EN.pdf

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